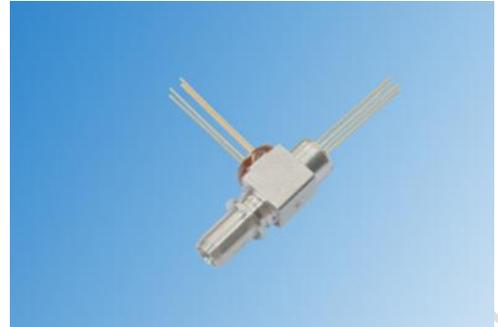


ETRR51xxK3x3CKxx

With 1.55um 1.25G MQW-FP WDM Laser Diode and PIN/TIA 155Mbps~2.5Gbps transmission



Features

- ◆ Coaxial package
- ◆ InGaAsP/InP MQW-FP laser diode
- ◆ Low threshold, high slope efficiency and high output power
- ◆ Operating case temperature: -40°C to +85°C
- ◆ single -mode fiber-stub with ST connector
- ◆ Low return loss

Applications

- ◆ Long distance digital transmission system
- ◆ Cable television system
- ◆ WDM systems
- ◆ Compatible with 100M/1000Mbps

Absolute maximum ratings

Parameter	Symbol	Ratings	Unit
Storage temperature	Tstg	-40~+85	°C
Operating case temperature	Top	-40~+85	°C
Operation relative Humidity		85	%
Forward current (LD)	IFD	150	mA
Monitor PD reverse voltage (LD)	VrL	2	V
Monitor PD reverse voltage (PD)	VrP	20	V
Monitor PD reverse current (PD)	IrP	2	mA
PD reverse voltage	Vpd	15	V
TIA supply voltage	Vcc	3.0~5.0	V
Soldering temperature (<10s)	Stemp	260	°C

Electrical and optical characteristics - transmitter

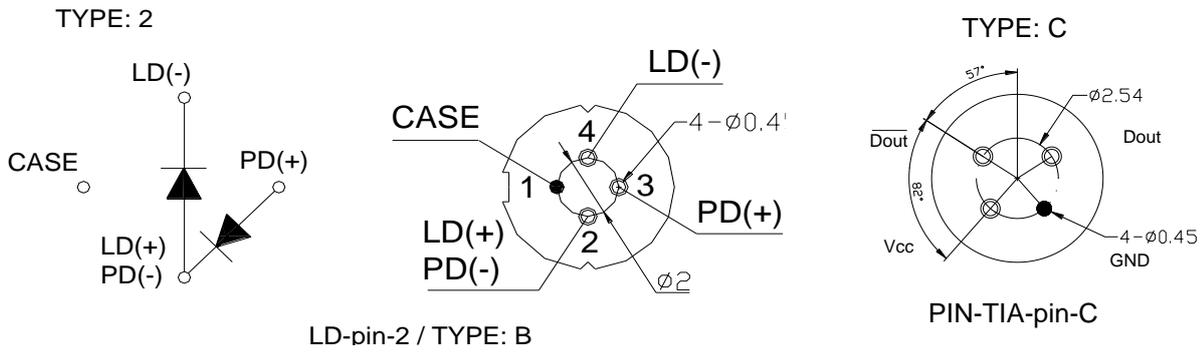
($I_f=I_{th}+20\text{mA}$, $P_f=0.4\text{mW}$, $\text{SMF}(9.5/125\mu\text{m})$, $T_c=+25+/-2^\circ\text{C}$, unless otherwise noted.)

Parameter	Symbol	Min.	Typ	Max	Unit	Test Condition
Threshold current	I_{th}	3	5	10	mA	CW
Output power (after coupled)	P_f	0.2	0.5	0.99	mW	CW, $I_f=I_{th}+20\text{mA}$
Operating voltage	V_f	—	1.2	1.6	V	CW, $T_c=-40\sim+85^\circ\text{C}$
Slope efficiency	S_e	0.01	0.025	0.035	mW/mA	CW, $I_f=I_{th}+20\text{mA}$
Peak wavelength	λ_p	1520	1550	1580	nm	CW
Spectral width	$\Delta\lambda$	—	1.5	3	nm	CW, RMS
Rise and fall time	t_r, t_f	—	0.1	0.25	ns	$I_b=I_{th}$, 20~80%
Monitor current (PD)	I_m	0.05	0.2	0.6	mA	CW, $I_f=I_{th}+20\text{mA}$ VRD=5V
Dark current (PD)	I_d	—	—	0.01	μA	VRD=5V
Capacitance (PD)	C_t	—	10	20	pF	VRD=5V, $f=1\text{MHz}$
Connector repeatability	—	-1	—	1	dB	—

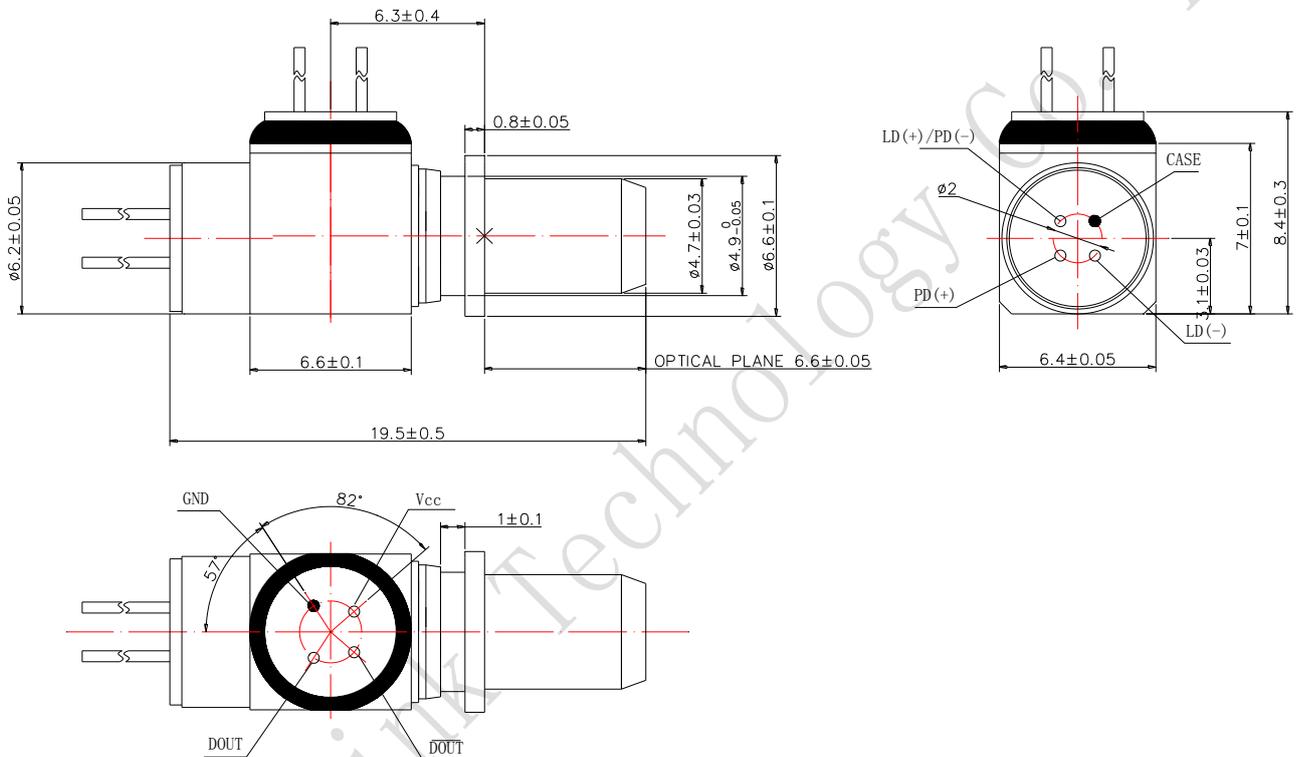
Electrical / optical specifications - receiver

Parameter	Symbol	Min	Typ	Max	Unit	Test condition
Operating Wavelength	λ	1260	—	1360	nm	
Supply Voltage	V_{cc}	3.0	3.3	5	V	
Supply current	I_{cc}	23	—	35	mA	$V_{cc}=3.3\text{V}$
Saturation power	P_{sat}	-3	0	—	dBm	
Output impedance	Z_o	—	50	—	Ω	Single ended
Small-signal bandwidth	BW	115			MHz	$\lambda=1310\text{nm}, 155\text{M}$, PRBS=27-1, BER=10-10, ER=9dB
Sensitivity	S_{en}		-37	-35	dBm	
Small-signal bandwidth	BW	435			MHz	$\lambda=1310\text{nm}, 622\text{M}$, PRBS=27-1, BER=10-10, ER=9dB
Sensitivity	S_{en}	—	-32	-30	dBm	
Small-signal bandwidth	BW	730			MHz	$\lambda=1310\text{nm}, 1.25\text{G}$, PRBS=27-1, BER=10-10, ER=9dB
Sensitivity	S_{en}	—	-28	-25	dBm	
Small-signal bandwidth	BW	1.4			GHz	$\lambda=1310\text{nm}, 2.5\text{G}$, PRBS=27-1, BER=10-10, ER=9dB
Sensitivity	S_{en}	—	-23	-21	dBm	B

Pin assignment

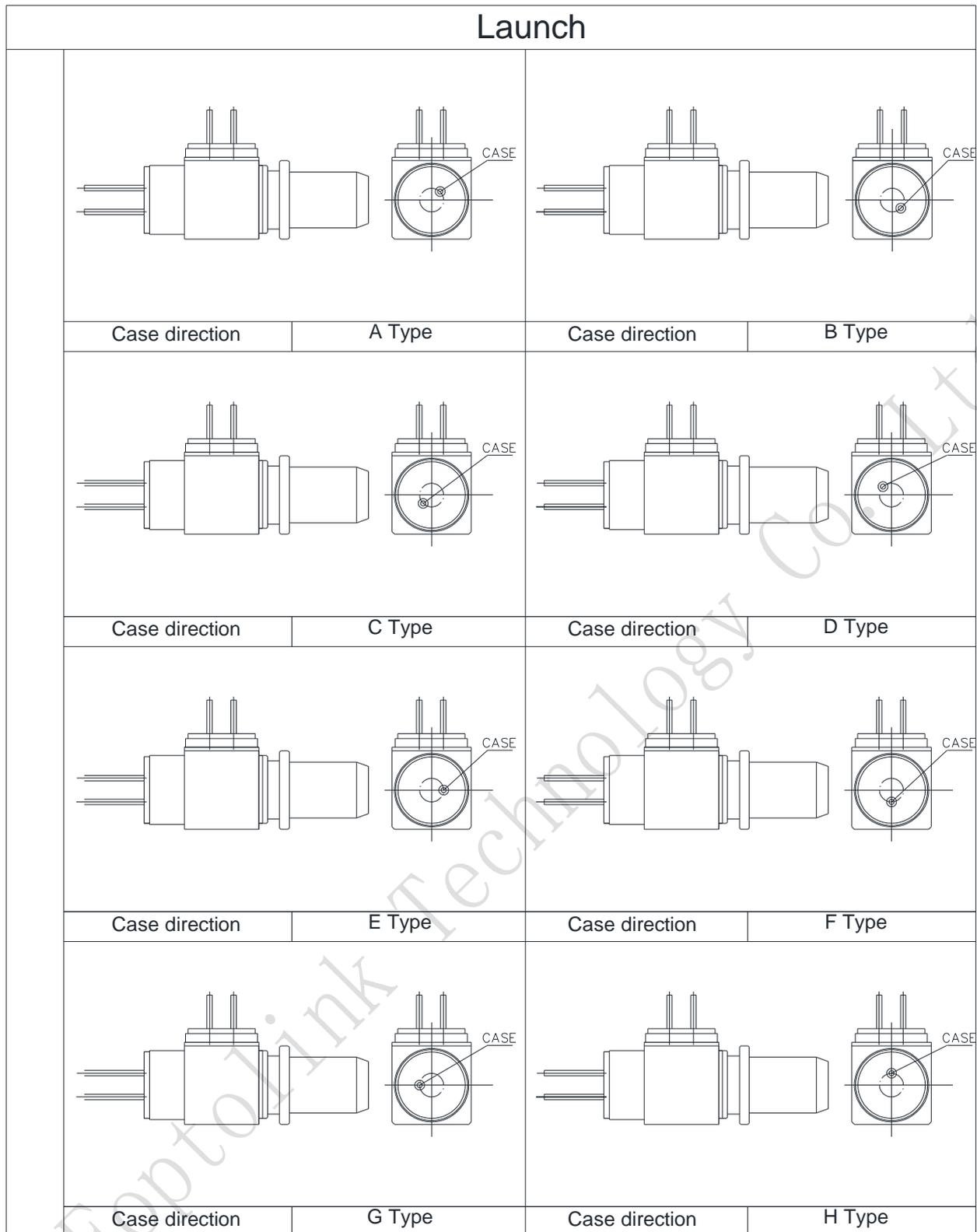


Package dimension ^{*Note1}



Note1: PIN direction and laser mark can be customized.

TX pin order code



1、 This picture is for pluggable, pigtail BIDI chip PIN package direction's reference

2、 This picture is suitable for RX Pin direction comparison .

The package direction is described as "x-x" For example "A-B", "A" is TX chip Pin direction, "B" is RX chip Pin direction.

RX pin order code

Receive	
Case direction	A Type
Case direction	C Type
Case direction	E Type
Case direction	G Type
Case direction	H Type

Ordering information (standard version) ^{*Note2}

Part No	Laser type	Receiving rate	Transmitter/Receiver
ETRR5104K330CKAA	FP	155M	15T/13R
ETRR5108K353CKAA	FP	622M	15T/13R
ETRR5104K373CKAA	FP	1.25G	15T/13R
ETRR5104K393CKAA	FP	2.5G	15T/13R

Note2: For more ordering information, please refer to nomenclature or contact EOPTOLINK sales.

ETRR

A B C D E F G H I J K L

Code	Parameter	Detailed description								
A	Launch wavelength	5=1550nm								
B	Launch data rate	1=1.25Gbps								
C	Output power	04=0.25~0.7mW	08=0.71~1.29 mW	15=1.3~1.79 mW						
E	TX chip type	K=EO								
F	Receiver wavelength	3=1310nm								
G	Receiver data rate	3=155M	5=622M	7=1.25G	9=2.5G					
H	Receiver voltage	0=3.3/5V		3=3.3V			5=5V			
I	RX pin type	C=PIN-TIA-pin-C								
J	RX chip type	K=EO								
K	TX pin package direction	A	B	C	D	E	F	G	H	
L	RX pin package direction	A	B	C	D	E	F	G	H	

Precaution

- (1) The modules should be handled in the same manner as ordinary semiconductor devices to prevent the electro-static damages. For safe keeping and carrying, the modules should be packaged with ESD proof material. To assemble the modules on PCB, the workbench, the soldering iron and the human body should be grounded.
- (2) Please pay special attention to the atmosphere condition because the dew on the module may cause some electrical damages.
- (3) Under such a strong vibration environment as in automobile, the performance and reliability are not guaranteed.

Obtaining document

You can visit our website:

<http://www.eoptolink.com>

Or contact Eoptolink Technology Inc., Ltd. listed at the end of the documentation to get the latest documentation.

Eoptolink Technology Inc., Ltd.

Revision history

Version	Initiated	Reviewed	Approved	Revision history	Release date
Va-1	Yinchun.Zhao	James.liu	Vincent	Released	2019-11-15

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